

SOT38-1

plastic dual in-line package; 16 leads (300 mil); long body

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP16
Package type industry code	DIP16
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	050G09
JEDEC package outline code	MO-001
JEITA package outline code	SC-503-16
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

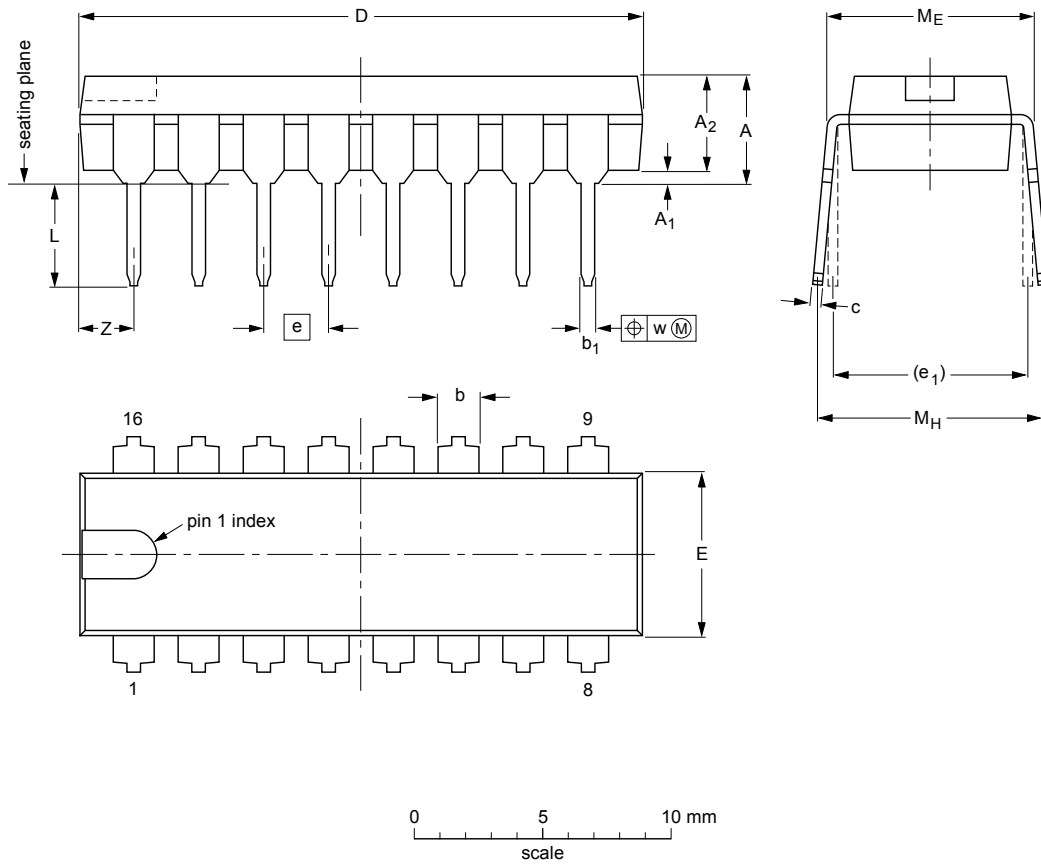
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.6	21.8	mm
E	package width	6.2	-	6.35	6.48	mm
A	seated height	[tbd]	-	4.7	4.7	mm
A ₂	package height	[tbd]	-	3.55	3.7	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.02	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.1	0.3	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT38-1	050G09	MO-001	SC-503-16		99-12-27 03-02-13

Fig. 1. Package outline DIP16 (SOT38-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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Date of release: 8 February 2016
